

# PHOTOCOUPLER PS2911-1

## HIGH CTR, 4-PIN ULTRA SMALL PACKAGE FLAT-LEAD PHOTOCOUPLER

-NEPOC Series-

### **DESCRIPTION**

The PS2911-1 is an optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor in one package for high density mounting applications.

An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 30% compared with the PS28xx series.

#### **FEATURES**

- Ultra small flat-lead package (4.6 (L) × 2.5 (W) × 2.1 (H) mm)
- High current transfer ratio (CTR = 200% TYP. @ I<sub>F</sub> = 1 mA, V<sub>CE</sub> = 5 V)
- High isolation voltage (BV = 2 500 Vr.m.s.)
- Ordering number of taping product: PS2911-1-F3, F4: 3 500 pcs/reel

<R>

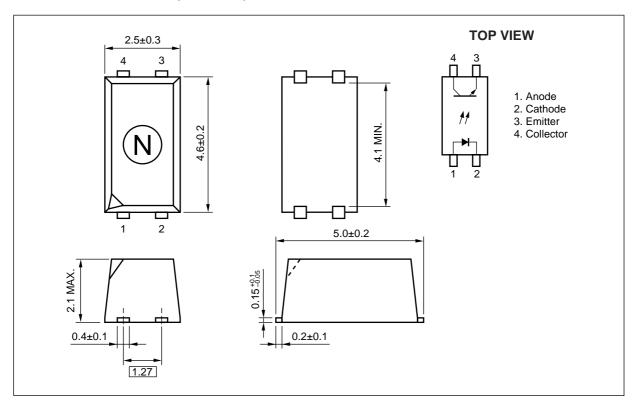
- · Safety standards
  - UL approved: File No. E72422
  - BSI approved: No. 8657, 8658
  - DIN EN60747-5-2 (VDE0884 Part2) approved (Option)

### **APPLICATIONS**

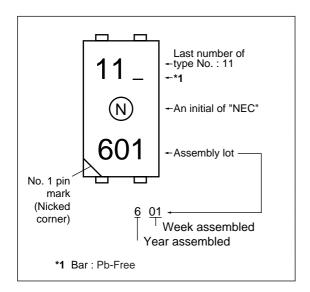
- DC/DC converter
- Modem/PC card

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

### PACKAGE DIMENSIONS (UNIT: mm)



### <R> MARKING EXAMPLE



### PHOTOCOUPLER CONSTRUCTION

Parameter	Unit (MIN.)		
Air Distance	4 mm		
Creepage Distance	4 mm		
Isolation Distance	0.4 mm		

### <R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*
PS2911-1	PS2911-1-A	Pb-Free	50 pcs (Tape 50 pcs cut)	Standard products	PS2911-1
PS2911-1-F3	PS2911-1-F3-A		Embossed Tape 3 500 pcs/reel	(UL, BSI approved)	
PS2911-1-F4	PS2911-1-F4-A				
PS2911-1-V	PS2911-1-V-A		50 pcs (Tape 50 pcs cut)	DIN EN60747-5-2	
PS2911-1-V-F3	PS2911-1-V-F3-A		Embossed Tape 3 500 pcs/reel	(VDE0884 Part2)	
PS2911-1-V-F4	PS2911-1-V-F4-A			Approved (Option)	

<sup>\*1</sup> For the application of the Safety Standard, following part number should be used.

### ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current Forward Current Derating		50	mA	
			0.5	mA/°C	
	Peak Forward Current*1	IFP	0.5	Α	
	Power Dissipation	Po	60	mW	
	Reverse Voltage	VR	6	V	
Transistor	Collector to Emitter Voltage	Vceo	40	V	
	Emitter to Collector Voltage	Veco	5	V	
	Collector Current	lc	40	mA	
	Power Dissipation Derating	⊿Pc/°C	1.2	mW/°C	
	Power Dissipation	Pc	120	mW	
Isolation Voltage *2		BV	2 500	Vr.m.s.	
Total Power Dissipation		Рт	160	mW	
Operating Ambient Temperature		TA	-55 to +100	°C	
Storage Temperature		T <sub>stg</sub>	-55 to +150	°C	

<sup>\*1</sup> PW = 100  $\mu$ s, Duty Cycle = 1%

<sup>\*2</sup> AC voltage for 1 minute at  $T_A$  = 25°C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

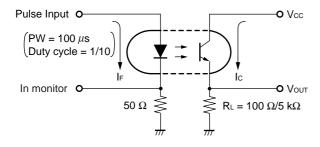
### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 1 mA	0.9	1.1	1.3	V
	Reverse Current	lR	V <sub>R</sub> = 5 V			5	μА
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		15		pF
Transistor	Collector to Emitter Dark Current	ICEO	IF = 0 mA, VcE = 40 V			100	nA
Coupled	Current Transfer Ratio	CTR	IF = 1 mA, VcE = 5 V	100	200	400	%
	Collector Saturation Voltage	VCE (sat)	IF = 1 mA, Ic = 0.2 mA		0.13	0.3	V
	Isolation Resistance	R <sub>I-O</sub>	Vi-o = 1 kVDC	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
	Rise Time*2	tr	$Vcc = 5 \text{ V}, \text{ Ic} = 2 \text{ mA}, \text{ RL} = 100 \Omega$		5		μS
	Fall Time*2	<b>t</b> f			10		
	On Time <sup>*2</sup>	ton	$Vcc = 5 \text{ V}, \text{ If } = 1 \text{ mA}, \text{ RL} = 5 \text{ k}\Omega$		40		μS
	Storage Time *2	<b>t</b> s			10		μS
	Off Time*2	<b>t</b> off			120		μS

### \*1 CTR rank

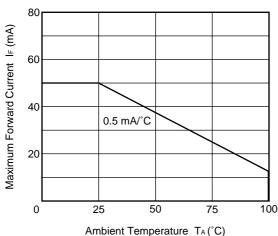
N: 100 to 400 (%) K: 200 to 400 (%) L: 150 to 300 (%) M: 100 to 200 (%)

### \*2 Test circuit for switching time

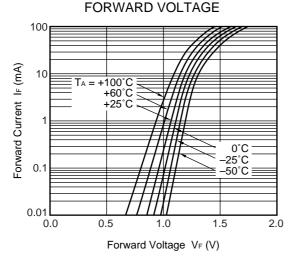


### TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

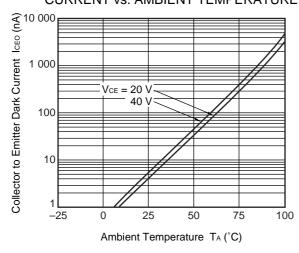




### FORWARD CURRENT vs.

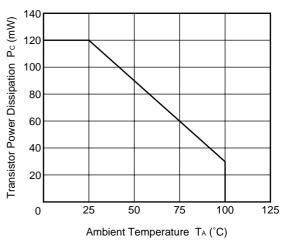


### COLLECTOR TO EMITTER DARK **CURRENT vs. AMBIENT TEMPERATURE**

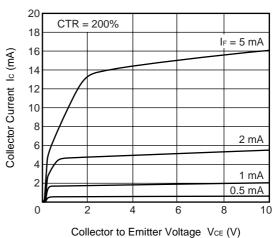


Remark The graphs indicate nominal characteristics.

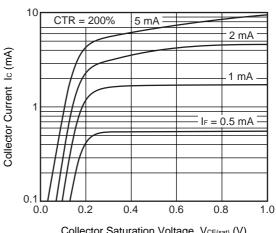
### TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



### COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE

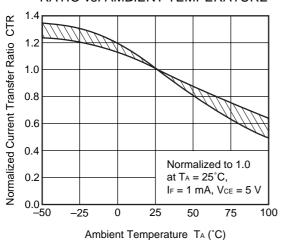


### COLLECTOR CURRENT vs. **COLLECTOR SATURATION VOLTAGE**

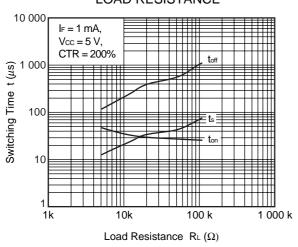


Collector Saturation Voltage VCE(sat) (V)

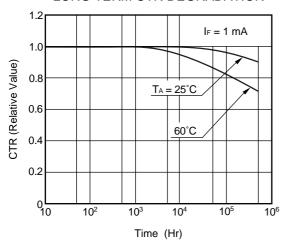
### NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



### SWITCHING TIME vs. LOAD RESISTANCE

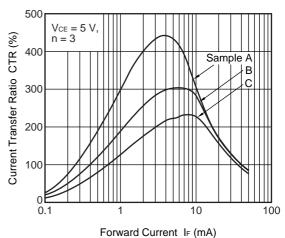


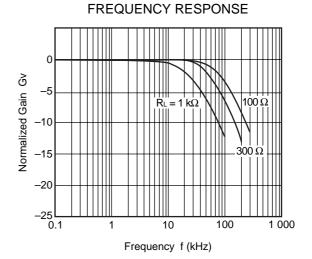
### LONG TERM CTR DEGRADATION



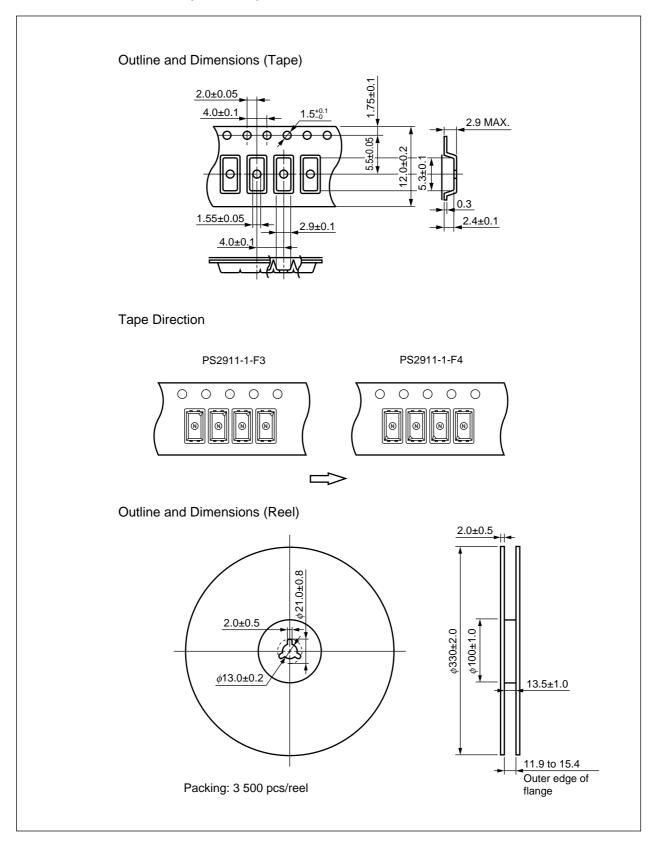
**Remark** The graphs indicate nominal characteristics.

### CURRENT TRANSFER RATIO vs. FORWARD CURRENT

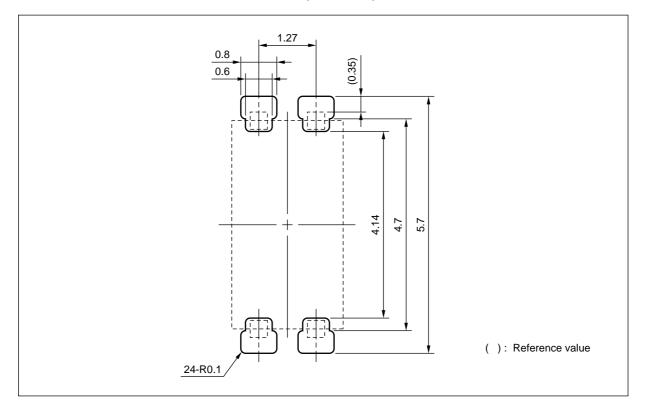




### TAPING SPECIFICATIONS (UNIT: mm)



### RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



**Remark** This drawing is considered to meet air and outer creepage distance 4.0 mm minimum. All dimensions in this figure must be evaluated before use.

### **NOTES ON HANDLING**

### 1. Recommended soldering conditions

### (1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

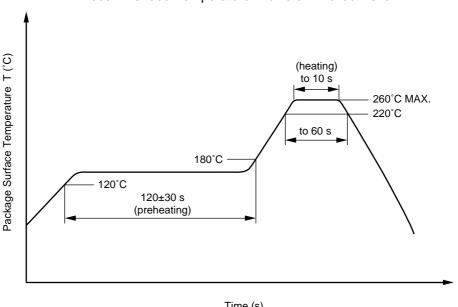
• Time of peak reflow temperature 10 seconds or less • Time of temperature higher than 220°C 60 seconds or less

• Time to preheat temperature from 120 to 180°C 120±30 s · Number of reflows Three

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

### Recommended Temperature Profile of Infrared Reflow



Time (s)

### (2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

· Preheating conditions 120°C or below (package surface temperature)

· Number of times One (Allowed to be dipped in solder including plastic mold portion.)

• Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

#### <R> (3) Soldering by soldering iron

• Peak temperature (lead part temperature) 350°C or below • Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

### (4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

### 2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

### <R> 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

### **USAGE CAUTIONS**

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

- The information in this document is current as of May, 2006. The information is subject to change
  without notice. For actual design-in, refer to the latest publications of NEC Electronics data sheets or
  data books, etc., for the most up-to-date specifications of NEC Electronics products. Not all
  products and/or types are available in every country. Please check with an NEC Electronics sales
  representative for availability and additional information.
- No part of this document may be copied or reproduced in any form or by any means without the prior
  written consent of NEC Electronics. NEC Electronics assumes no responsibility for any errors that may
  appear in this document.
- NEC Electronics does not assume any liability for infringement of patents, copyrights or other intellectual
  property rights of third parties by or arising from the use of NEC Electronics products listed in this document
  or any other liability arising from the use of such products. No license, express, implied or otherwise, is
  granted under any patents, copyrights or other intellectual property rights of NEC Electronics or others.
- Descriptions of circuits, software and other related information in this document are provided for illustrative
  purposes in semiconductor product operation and application examples. The incorporation of these
  circuits, software and information in the design of a customer's equipment shall be done under the full
  responsibility of the customer. NEC Electronics assumes no responsibility for any losses incurred by
  customers or third parties arising from the use of these circuits, software and information.
- While NEC Electronics endeavors to enhance the quality, reliability and safety of NEC Electronics products, customers agree and acknowledge that the possibility of defects thereof cannot be eliminated entirely. To minimize risks of damage to property or injury (including death) to persons arising from defects in NEC Electronics products, customers must incorporate sufficient safety measures in their design, such as redundancy, fire-containment and anti-failure features.
- NEC Electronics products are classified into the following three quality grades: "Standard", "Special" and
  "Specific".
  - The "Specific" quality grade applies only to NEC Electronics products developed based on a customer-designated "quality assurance program" for a specific application. The recommended applications of an NEC Electronics product depend on its quality grade, as indicated below. Customers must check the quality grade of each NEC Electronics product before using it in a particular application.
  - "Standard": Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots.
  - "Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).
  - "Specific": Aircraft, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems and medical equipment for life support, etc.

The quality grade of NEC Electronics products is "Standard" unless otherwise expressly specified in NEC Electronics data sheets or data books, etc. If customers wish to use NEC Electronics products in applications not intended by NEC Electronics, they must contact an NEC Electronics sales representative in advance to determine NEC Electronics' willingness to support a given application.

#### (Note)

- (1) "NEC Electronics" as used in this statement means NEC Electronics Corporation and also includes its majority-owned subsidiaries.
- (2) "NEC Electronics products" means any product developed or manufactured by or for NEC Electronics (as defined above).

M8E 02.11-1

### Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
  - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
  - 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

### ▶ For further information, please contact

### **NEC Compound Semiconductor Devices Hong Kong Limited**

E-mail: contact@ncsd-hk.necel.com

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309
Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859
Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

#### NEC Electronics (Europe) GmbH http://www.eu.necel.com/

TEL: +49-211-6503-0 FAX: +49-211-6503-1327

California Eastern Laboratories, Inc. http://www.cel.com/

TEL: +1-408-988-3500 FAX: +1-408-988-0279

Compound Semiconductor Devices Division NEC Electronics Corporation URL: http://www.ncsd.necel.com/